

PRODUCT DATA SHEET

Sikafloor®-161 HC

Multipurpose epoxy primer and binder for levelling screeds and mortars

DESCRIPTION

Sikafloor®-161 HC is a 2-part, low viscosity multipurpose filled epoxy resin for priming and levelling concrete and cementitious substrates.

USES

Sikafloor®-161 HC may only be used by experienced professionals.

- For priming concrete substrate, cement screeds and epoxy mortars
- For low to medium absorbent substrates
- Primer for the Sikafloor®-264 HC N flooring systems
- Binder for levelling mortars and mortar screeds
- Intermediate layer underneath of Sikafloor®-264 HC

CHARACTERISTICS / ADVANTAGES

- Low viscosity
- Good penetration
- Excellent bond strength
- Solvent free
- Easy application
- Short waiting times
- Multi-purpose

PRODUCT INFORMATION

Chemical base	Ероху		
Packaging	Part A+B	20 kg set	
	Part A	15.8 kg co	ontainer
	Part B	4.2 kg cor	ntainer
Shelf life	12 months from date of production if stored properly in original, unopened and undamaged sealed packaging.		
Storage conditions	The product must be stored in original, unopened and undamaged sealed packaging in dry conditions at temperatures between +10 °C and +30 °C		
Appearance / Colour	Part A – Resin	Liquid, br	ownish-transparent
	Part B – Hardener	Liquid, ye	llow-transparent
Density	Part A	~1.6 kg/L	(DIN EN ISO 2811-1)
	Part B	~1.0 kg/L	(at +30 °C)
	Mixed Resin	~1.45 kg/L	
Solid content by weight	~100 %		

Product Data Sheet

Sikafloor®-161 HCDecember 2023, Version 04.01
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Shore D hardness	~76 (7 d, +27 °C)		(DIN 53 505)	
Compressive strength	~50 N/mm² (resin : Sika® Quartz 0	$^{\sim}50 \text{ N/mm}^2 \text{ (resin : Sika* Quartz 01 IN = 1 : 0.9) (28 d, +27 °C)}$		
Flexural strength	~30 N/mm² (resin : Sika® Quartz 0	01 IN = 1 : 0.9)(28 d, +27 °C)	(EN 196-1)	
Tensile adhesion strength	> 1.5 N/mm² (failure in concrete)		(EN 1542)	
Heat resistance	IMPORTANT No simultaneous mechanical and While the product is exposed to t subject it to chemical and/or med the product.	emperatures up to +60 °C, do		
	Exposure	Dry heat		
	Short-term, maximum 7 days	+60 °C		
Chemical resistance	Resistant to many chemicals. Plea	ase ask for a detailed chemica	al resistance	

SYSTEM INFORMATION

Systems Pr

Low / medium porosity concrete	1-2 × Sikafloor®-161 HC
High porosity concrete	2 × Sikafloor®-161 HC

Bonding bridge:

Bonding bridge	1 × Sikafloor®-161 HC

Levelling mortar fine (surface roughness < 1 mm):

Primer	1–2 × Sikafloor®-161 HC
Levelling mortar	1 × Sikafloor®-161 HC + Sika® Quartz
	04 IN

Levelling mortar medium (surface roughness up to 2 mm):

Primer	1–2 × Sikafloor®-161 HC
Levelling mortar	1 × Sikafloor®-161 HC + Sika® Quartz
	01 IN

Resin screed (15 mm to 20 mm layer thickness) / Repair mortar:

Primer	1-2 × Sikafloor®-161 HC
Bonding bridge	1 × Sikafloor®-161 HC
Screed	1 × Sikafloor®-161 HC + suitable
	sand mixture

The following sand mixtures are indicative mix design quantities that must be confirmed by pre-trials. Grain size distribution for layer thicknesses of 15–20 mm, parts by weight (pbw):

- 25 pbw quartz sand 0.1–0.5 mm
- 25 pbw quartz sand 0.4–0.7 mm
- 25 pbw quartz sand 0.7–1.2 mm
- 25 pbw quartz sand 2–4 mm

Note: The largest grain size may not exceed 1/3 of the finished layer thickness. Dependent on the grain shape and application temperatures, the sand and the most suitable mix must be selected and confirmed by pre-trials.

APPLICATION INFORMATION

Product Data Sheet Sikafloor®-161 HC December 2023, Version 04.01 020811020010000053



Consumption	Coating System	Produc	<u>t </u>	Consumption
	Priming	Sikafloo	or®-161 HC	0.25-0.50 kg/m ²
	Bonding bridge		or®-161 HC	0.25-0.50 kg/m ²
	Levelling mortar fi		Sikafloor®-161	1.7 kg/m²/mm
	(surface roughnes		5 pbw Sika®	
	mm)	Quartz		
	Levelling mortar n		Sikafloor®-161	1.8 kg/m²/mm
	um (surface rough		8 pbw Sika®	
	up to 2 mm)	Quartz		2.21/2/
	Epoxy screed (15-	•	Sikafloor®-161	2.2 kg/m ² /mm
	mm layer thicknes Repair mortar	55)/ NC + /	pbw quartz sand	
		es are theoretic	al and do not all	ow for any additional ma
				ofile, variations in level,
		-		et to a test area to calcu-
	= -			ate conditions and pro-
	posed application	•	·	•
Ambient air temperature	+10 °C min. / +30	°C max.		
Relative air humidity	80 % r.h. max.			
Dew point	Beware of conden			
				+3 °C above dew point to
	reduce the risk of		_	
		_	h humidity condi	tions increase the prob-
	ability of blooming			
	+10 °C min. / +30 °C max.			
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BASIS OF PRODUCT DATA

All technical data stated in this Product Data Sheet are based on laboratory tests. Actual measured data may vary due to circumstances beyond our control.

ECOLOGY, HEALTH AND SAFETY

User must read the most recent corresponding Safety Data Sheets (SDS) before using any products. The SDS provides information and advice on the safe handling, storage and disposal of chemical products and contains physical, ecological, toxicological and other safety-related data.

APPLICATION INSTRUCTIONS

SUBSTRATE QUALITY

- The concrete substrate must be sound and of sufficient compressive strength (minimum 25 N/mm²) with a minimum pull off strength of 1.5 N/mm².
- The substrate must be clean, dry and free of all contaminants such as dirt, oil, grease, coatings and surface treatments, etc.

SUBSTRATE PREPARATION

MECHANICAL SUBSTRATE PREPARATION **IMPORTANT**

Exposing blow holes and voids

When mechanically preparing the surface, make sure to fully expose blow holes and voids.

- 1. Remove weak cementitious substrates.
- 2. Prepare cementitious substrates mechanically using abrasive blast cleaning or planing / scarifying equipment or grinding to remove cement laitance.
- 3. Before applying thin layer resins, remove high spots by grinding.
- 4. Use industrial vacuuming equipment to remove all dust, loose and friable material from the application surface before applying the Product.
- 5. Use products from the Sikafloor®, Sikadur® and Sikagard® range of materials to level the surface or fill cracks, blow holes and voids.

Contact Sika® Technical Services for additional information on products for levelling and repairing defects. TREATMENT OF JOINTS AND CRACKS

Construction joints and existing static surface cracks in substrate require pre-treating before full layer application. Use Sikadur® or Sikafloor® resins.

MIXING

Note: To increase the viscosity of the Product you can add Sika® Extender T or Sikafloor® Quartz Flour.

PRIMER MIXING PROCEDURE

- 1. Mix Part A (resin) for ~30 seconds.
- 2. Add Part B (hardener) to Part A.
- 3. IMPORTANT Do not mix excessively. Mix Part A + B continuously for ~3 minutes until a uniform mix is
- 4. To ensure thorough mixing, pour materials into another container and mix again to achieve a smooth and uniform mix.

plete mixing. LEVELLING MORTAR AND RESIN SCREED MIXING PRO-

5. During the final mixing stage, scrape down the sides

and bottom of the mixing container with a flat or straight edge trowel at least once to ensure com-

CEDURE

- 1. Mix Part A (resin) for ~30 seconds.
- 2. Add Part B (hardener) to Part A.
- 3. While mixing Parts A + B, gradually add the required filler or aggregates.
- 4. IMPORTANT Do not mix excessivley. Mix for a further 2 minutes until a uniform mix is achieved.
- 5. To ensure thorough mixing, pour materials into another container and mix again to achieve a smooth and uniform mix.
- 6. During the final mixing stage, scrape down the sides and bottom of the mixing container with a flat or straight edge trowel at least once to ensure complete mixing.

MIXING TOOLS

Sikafloor®-161 HC must be thoroughly mixed using a low speed electric stirrer (300 - 400 rpm) or other suitable equipment. For the preparation of mortars use a forced action mixer of rotating pan, paddle or trough type. Free fall mixers should not be used.

APPLICATION

IMPORTANT

Protect from moisture

Prior to application, confirm substrate moisture content, r.h. and dew point.

If > 4 % pbw moisture content, Sikafloor® EpoCem® may be applied as a T.M.B. (temporary moisture barrier) system.

After application, protect the Product from damp, condensation and direct water contact for at least 24 hours.

Pin holes

If the Product is applied on porous substrates during rising temperatures, pin holes may form from rising

1. Apply the Product during falling temperatures.

Closing Pin holes

If pin holes are present after the Product has cured blistering may occur in the subsequent layer. Close any pin holes using the following steps.

- 1. Lightly grind the cured surface.
- 2. Apply a scratch coat consisting of the Product Sikafloor®-161 HC mixed with Sikafloor® Quartz Flour or Sika® Extender T.

STANDARD PRIMER APPLICATION

- 1. Pour the mixed Product onto the substrate. Note: The consumption is specified in Application Informa-
- 2. Apply the Product evenly over the surface with a short pile roller or a squeegee.
- 3. Back roll the surface in two directions at right angles with a fleece roller. Note: Maintain a "wet edge" during application to achieve a seamless finish.
- 4. If broadcasting is required, wait between 15 and 30 minutes, then broadcast the surface with quartz sand. Broadcast lightly at first, then to excess.



5. IMPORTANT Confirm waiting or overcoating time is achieved before applying subsequent products. (Refer to the "waiting time to overcoating" section of Application Information). Once the product has hardened sufficiently, remove all loose sand with industrial vacuuming equipment.

LEVELLING MORTAR / SCRATCH COAT

Equipment:

- Squeegee
- Trowel
- 1. Pour the mixed Product onto the substrate. Note: The consumption is specified in Application Informa-
- 2. Apply the Product evenly over the surface with a trowel or a squeegee.

BONDING BRIDGE

- 1. Pour the mixed Product onto the substrate. Note: The consumption is specified in Application Informa-
- 2. Apply the Product evenly over the surface with a brush, fleece roller or a squeegee.
- 3. Back roll the surface in two directions at right angles with a fleece roller. Note: Maintain a "wet edge" during application to achieve a seamless finish.
- 4. (Optional) If required, apply a second priming coat.

RESIN SCREED

IMPORTANT

Not suitable for contact with water

The Product is not suitable for contact with water unless sealed with seal coat.

- 1. Pour the mixed Product "wet on wet" onto the still tacky primer. Note: The consumption is specified in Application Information.
- 2. Spread and compact the Product with a trowel to the required thickness between screed rails / battens, if installed.
- 3. Level the screed surface with a levelling beam spanning onto the screed rails / battens.
- 4. Finish the surface to the required surface texture with trowels or walk-behind power floats.

RESIN PATCH REPAIR MORTAR

- 1. Pour the mixed Product "wet on wet" onto the still tacky primer.
- 2. Apply the Product with a trowel to the required thickness.
- 3. Compact the applied product with a trowel.
- 4. IMPORTANT Confirm waiting or overcoating time is achieved before applying subsequent products. (Refer to the "waiting time to overcoating" section of Application Information). Smoothen the surface with a trowel.

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Product Data Sheet Sikafloor®-161 HC December 2023, Version 04.01 020811020010000053



Clean all tools and application equipment with Thinner C immediately after use. Hardened / cured material can only be mechanically removed.

LOCAL RESTRICTIONS

Note that as a result of specific local regulations the declared data and recommended uses for this product may vary from country to country. Consult the local Product Data Sheet for exact product data and uses.

LEGAL NOTES

The information, and, in particular, the recommendations relating to the application and end-use of Sika products, are given in good faith based on Sika's current knowledge and experience of the products when properly stored, handled and applied under normal conditions in accordance with Sika's recommendations. In practice, the differences in materials, substrates and actual site conditions are such that no warranty in respect of merchantability or of fitness for a particular purpose, nor any liability arising out of any legal relationship whatsoever, can be inferred either from this information, or from any written recommendations, or from any other advice offered. The user of the product must test the product's suitability for the intended application and purpose. Sika reserves the right to change the properties of its products. The proprietary rights of third parties must be observed. All orders are accepted subject to our current terms of sale and delivery. Users must always refer to the most recent issue of the local Product Data Sheet for the product concerned, copies of which will be supplied on request.

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